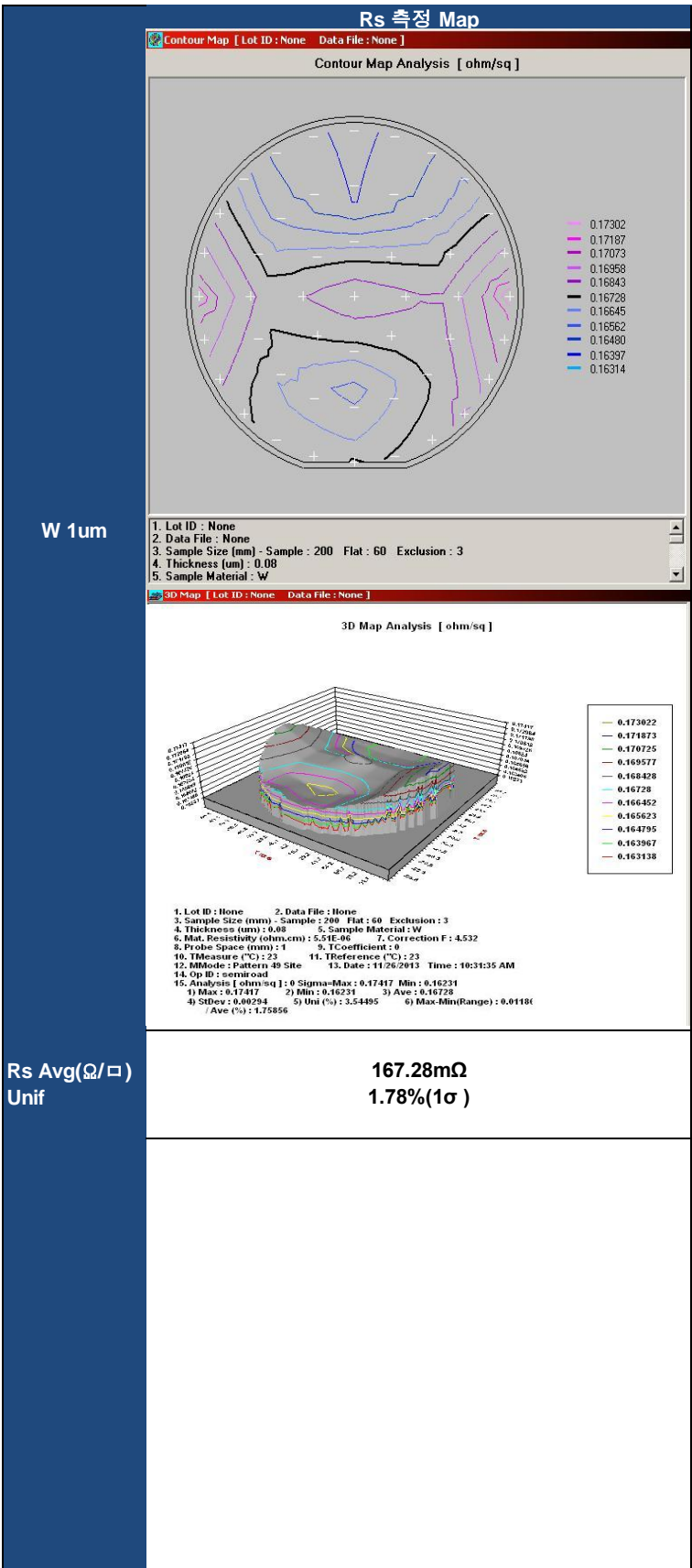


1. 공정명 : DC sputtering
2. 내용 : W 1um Deposition 1st wafer
3. wafer Size : 4inch Silicon wafer



Rs 측정	좌표		Condition
	x	y	RS
	(mm)	(mm)	mm/口
1	0.0	0.0	169.47
2	0.0	30.8	166.53
3	21.8	21.8	167.67
4	30.8	0.0	168.94
5	21.8	-21.8	167.78
6	0.0	-30.8	166.84
7	-21.8	-21.8	167.92
8	-30.8	0.0	168.46
9	-21.8	21.8	166.99
10	0.0	61.6	162.31
11	23.6	56.9	162.65
12	43.6	43.6	164.70
13	56.9	23.6	167.52
14	61.6	0.0	169.01
15	56.9	-23.6	167.67
16	43.6	-43.6	165.52
17	23.6	-56.9	164.15
18	0.0	-61.6	163.87
19	-23.6	-56.9	164.40
20	-43.6	-43.6	165.62
21	-56.9	-23.6	167.18
22	-61.6	0.0	168.16
23	-56.9	23.6	166.60
24	-43.6	43.6	164.09
25	-23.6	56.9	162.48
26	0.0	92.4	163.66
27	23.9	89.2	163.60
28	46.2	80.0	164.74
29	65.3	65.3	165.40
30	80.0	46.2	167.14
31	89.2	23.9	171.50
32	92.4	0.0	174.17
33	89.2	-23.9	173.53
34	80.0	-46.2	171.55
35	65.3	-65.3	169.81
36	46.2	-80.0	168.91
37	23.9	-89.2	165.97
38	0.0	-92.4	167.42
39	-23.9	-89.2	169.54
40	-46.2	-80.0	165.70
41	-65.3	-65.3	167.67
42	-80.0	-46.2	169.77
43	-89.2	-23.9	171.70
44	-92.4	0.0	172.92
45	-89.2	23.9	172.24
46	-80.0	46.2	169.20
47	-65.3	65.3	165.85
48	-46.2	80.0	163.83
49	-23.9	89.2	164.13

측정 Value	Max	mohm/sq	174.17
	Min	mohm/sq	162.31
	Avg	mohm/sq	167.28
	StDev	mohm/sq	2.97
	StDev(%)	%	1.78%